

Electronic Patent Application Fee Transmittal

Application Number:	10747621			
Filing Date:	30-Dec-2003			
Title of Invention:	Method of forming isolation structures in embedded semiconductor device			
First Named Inventor/Applicant Name:	Byeong Ryeol Lee			
Filer:	Eric Brett Compton/Febes B. Lazo			
Attorney Docket Number:	040008-0307457			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790